

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 3

DESC FORM 193A
FEB 86

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T _C < +125°C 4.5 V < V _{CC} < 5.5 V Unless otherwise specified	Group A subgroups	Limits		Unit	
				Min	Max		
High level output voltage	V _{OH}	V _{CC} = +4.5 V V _{IN} = 0.7 V or 2.0 V	Y outputs I _{OH} = -1.0 mA	1,2,3	2.4	V	
			I _{OH} = -440 μA CCO, RCO outputs	1,2,3	2.5	V	
Low level output voltage	V _{OL}	V _{CC} = +4.5 V V _{IN} = 0.7 V or 2.0 V	I _{OL} = 4.0 mA	1,2,3	0.4	V	
			I _{OL} = 8.0 mA	1,2,3	0.45	V	
Input clamp voltage	V _{IC}	I _{IN} = -18 mA V _{CC} = 4.5 V	1,2,3	-1.5	V		
High level input current	I _{IH1}	V _{CC} = 5.5 V V _{IN} = 2.7 V	1,2,3	20	μA		
	I _{IH2}	V _{CC} = 5.5 V V _{IN} = 7.0 V	1,2,3	100	μA		
Low level input current	I _{IL}	V _{CC} = 5.5 V V _{IN} = 0.4 V	ACLK, OE, U/D, LOAD	1,2,3	-300	μA	
			A, B, C, D, CP, CEP	1,2,3	-400	μA	
			CET, SCLR	1,2,3	-650	μA	
Off-state output current (high impedance)	I _{OZ}	V _{CC} = 5.5 V	V _{OUT} = 0.4 V	1,2,3	-20	μA	
			V _{OUT} = 2.4 V	1,2,3	20	μA	
Output short circuit current	I _{OS}	V _{CC} = 5.5 V V _{OUT} = 0.0 V	1/	1,2,3	-15	-85	mA
Power supply current	I _{CC}	V _{CC} = 5.5 V OE = High	All inputs = GND	1,2,3	43	mA	

See footnotes at end of table.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	DWG NO.
	A	5962-87544
	REV A	PAGE 4

DESC FORM 193A
FEB 86

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C 4.5 V ≤ V _{CC} ≤ 5.5 V Unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Functional testing		See 4.3.1c	7			
Propagation delay time clock to any Q T _{oad} = low	t _{PLH1}	R _{L1} = 5 kΩ R _{L2} = 2 kΩ (figure 4)	C _L = 50 pF <u>2/</u>	9,10,11	24	ns
			C _L = 15 pF <u>3/</u>	9	18	
	t _{PHL1}		C _L = 50 pF <u>2/</u>	9,10,11	35	ns
			C _L = 15 pF <u>3/</u>	9	21	
Propagation delay time clock to any Q T _{oad} = high	t _{PLH2}	R _{L1} = 5 kΩ R _{L2} = 2 kΩ (figure 4)	C _L = 50 pF <u>2/</u>	9,10,11	24	ns
			C _L = 15 pF <u>3/</u>	9	18	
	t _{PHL2}		C _L = 50 pF <u>2/</u>	9,10,11	35	ns
			C _L = 15 pF <u>3/</u>	9	21	
Propagation delay time CET to RCU	t _{PLH3}	R _{L1} = 2 kΩ (figure 4)	C _L = 50 pF <u>2/</u>	9,10,11	19	ns
			C _L = 15 pF <u>3/</u>	9	16	
	t _{PHL3}		C _L = 50 pF <u>2/</u>	9,10,11	21	ns
			C _L = 15 pF <u>3/</u>	9	14	

See footnotes at end of table.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE		DWG NO.	
	A		5962-87544	
	REV		PAGE	5

DESC FORM 193A
FEB 86

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C 4.5 V < V _{CC} < 5.5 V Unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Propagation delay time U/D to RCO	t _{PLH4}	R _L = 2 kΩ (figure 4)	C _L = 50 pF <u>2/</u>	9,10,11	28	ns
			C _L = 15 pF <u>3/</u>	9	23	
	t _{PHL4}		C _L = 50 pF <u>2/</u>	9,10,11	30	ns
			C _L = 15 pF <u>3/</u>	9	20	
Propagation delay time clock to RCO	t _{PLH5}	C _L = 50 pF <u>2/</u>	9,10,11	40	ns	
		C _L = 15 pF <u>3/</u>	9	35		
	t _{PHL5}	C _L = 50 pF <u>2/</u>	9,10,11	39	ns	
		C _L = 15 pF <u>3/</u>	9	26		
Propagation delay time clock to CCO	t _{PLH6}	C _L = 50 pF <u>2/</u>	9,10,11	18	ns	
		C _L = 15 pF <u>3/</u>	9	15		
	t _{PHL6}	C _L = 50 pF <u>2/</u>	9,10,11	27	ns	
		C _L = 15 pF <u>3/</u>	9	15		
Propagation delay time CET or CEP to CCO	t _{PLH7}	C _L = 50 pF <u>2/</u>	9,10,11	17	ns	
		C _L = 15 pF <u>3/</u>	9	15		
	t _{PHL7}	C _L = 50 pF <u>2/</u>	9,10,11	45	ns	
		C _L = 15 pF <u>3/</u>	9	25		

See footnotes at end of table.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 6

DESC FORM 193A
FEB 86

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C 4.5 V < V _{CC} < 5.5 V Unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
Propagation delay time ACL _R to any Q	t _{PLH8}	R _{L1} = 5 kΩ R _{L2} = 2 kΩ (figure 4)	C _L = 50 pF <u>2/</u>	9,10,11		N/A	ns
			C _L = 15 pF <u>3/</u>	9		N/A	
	t _{PHL8}		C _L = 50 pF <u>2/</u>	9,10,11		45	ns
			C _L = 15 pF <u>3/</u>	9		26	
Setup time A, B, C, D	t _{s1}		<u>2/</u>	9,10,11	30		ns
			<u>3/</u>	9	22		
Setup time SCLR	t _{s2}		<u>2/</u>	9,10,11	35		ns
			<u>3/</u>	9	20		
Setup time LOAD	t _{s3}		<u>2/</u>	9,10,11	45		ns
			<u>3/</u>	9	30		
Setup time U/D	t _{s4}		<u>2/</u>	9,10,11	45		ns
			<u>3/</u>	9	30		
Setup time CET, CEP	t _{s5}		<u>2/</u>	9,10,11	47		ns
			<u>3/</u>	9	32		
Setup time SCLR recovery time (inactive to clock)	t _{s6}		<u>2/</u>	9,10,11	50		ns
			<u>3/</u>	9	35		

See footnotes at end of table.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544	
		REV A	PAGE 7

DESC FORM 193A
FEB 86

TABLE I. Electrical performance characteristics - Continued.

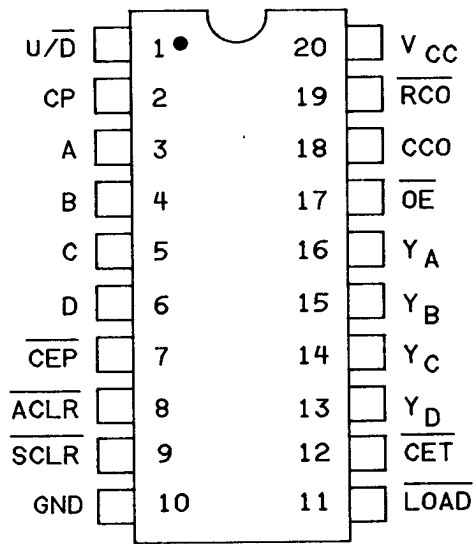
Test	Symbol	Conditions -55°C < T _C < +125°C 4.5 V < V _{CC} < 5.5 V Unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Data hold	t _H	2/	9,10,11	5		ns
			9	0		
Clock pulse width	t _{PW}	2/	9,10,11	37	1/37	ns
			9	25		
Enable time OE to any Q	t _{PZH}	R _{L1} = 5 kΩ R _{L2} = 2 kΩ (figure 4)	C _L = 50 pF 2/	9,10,11	20	ns
			C _L = 15 pF 3/	9	11	
Enable time OE to any clock	t _{PZL}		C _L = 50 pF 2/	9,10,11	34	ns
			C _L = 15 pF 3/	9	19	
Disable time OE to any Q	t _{PHZ}	C _L = 5 pF R _{L1} = 5 kΩ R _{L2} = 2 kΩ	2/	9,10,11	22	ns
			3/	9	18	
	t _{PLZ}		2/	9,10,11	36	ns
			3/	9	24	

- 1/ Not more than one output should be shorted at a time, and the duration of the short circuit condition should not exceed one second.
- 2/ Supply voltage = +4.5 V to +5.5 V, operating temperature = -55°C to +125°C.
- 3/ Supply voltage = +5.0 V, operating temperature = +25°C.

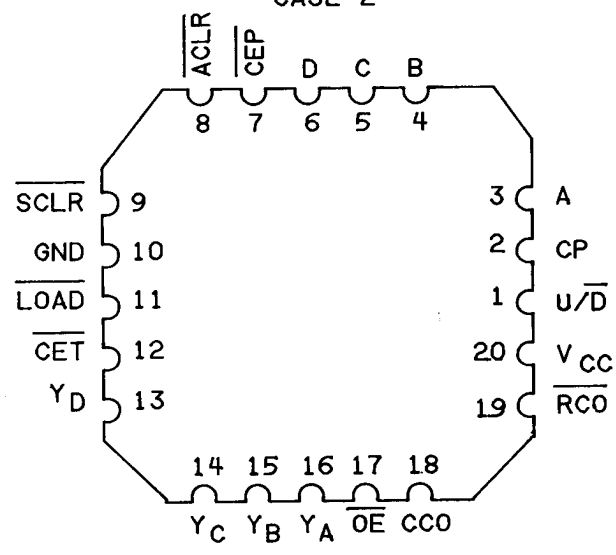
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 8

DESC FORM 193A
FEB 86

CASES R AND S



CASE 2



(TOP VIEW)

FIGURE 1. Terminal connections.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 9

DESC FORM 193A
FEB 86

MILITARY DRAWING										SIZE		DWG NO.							
DEFENSE ELECTRONICS SUPPLY CENTER																			
DAYTON, OHIO										REV		PAGE 10							
Mode	Inputs										Outputs								
	Load	CEP	CE	U/D	ASync	Sync	Clear	OE	D0	D1	D2	D3	CP	Q0	Q1	Q2	Q3	RC	Clock carry
Clear (async)	X	X	X	1	0	X	0	X	X	X	X	X	X	0	0	0	0	1	2/
Clear (sync)	X	X	X	0	0	X	0	X	X	X	X	.	.	0	0	0	0	0	2/
Load	0	X	1	X	1	1	0	X	X	X	X	.	.	0	Q _n =D _n	0	0	1	2/
Count up	1	0	0	1	1	1	0	X	X	X	X	.	.	1	1	1	1	0	2/
Count down	1	0	0	1	1	1	0	X	X	X	X	.	.	0	Q _n -1			0	4/
Inhibit	1	0	1	X	1	1	0	X	X	X	X	↑	↑	NC	NC	NC	NC	1	
Output disable	X	X	X	X	X	X	1	X	X	X	X	X	X	Z	Z	Z	Z	NC	NC

↑ = Clock low-to-high transition
 X = Don't care
 D_n = D₀ through D₃ input level prior to clock transition
 Q_n + 1 = Next higher count in binary sequence
 Q_n - 1 = Next lower count in binary sequence
 NC = No change

NOTES:
 1. Register performs at correct logic for any state of OE, but OE = 0 to view outputs.
 2. Follows clock if CE = 0, otherwise remains high.
 3. Low for one full clock cycle when maximum count is reached otherwise remains high.
 4. Follows clock when RC = 0.
 5. Low for one full clock cycle when minimum count is reached otherwise remains high.

FIGURE 2. Truth table.

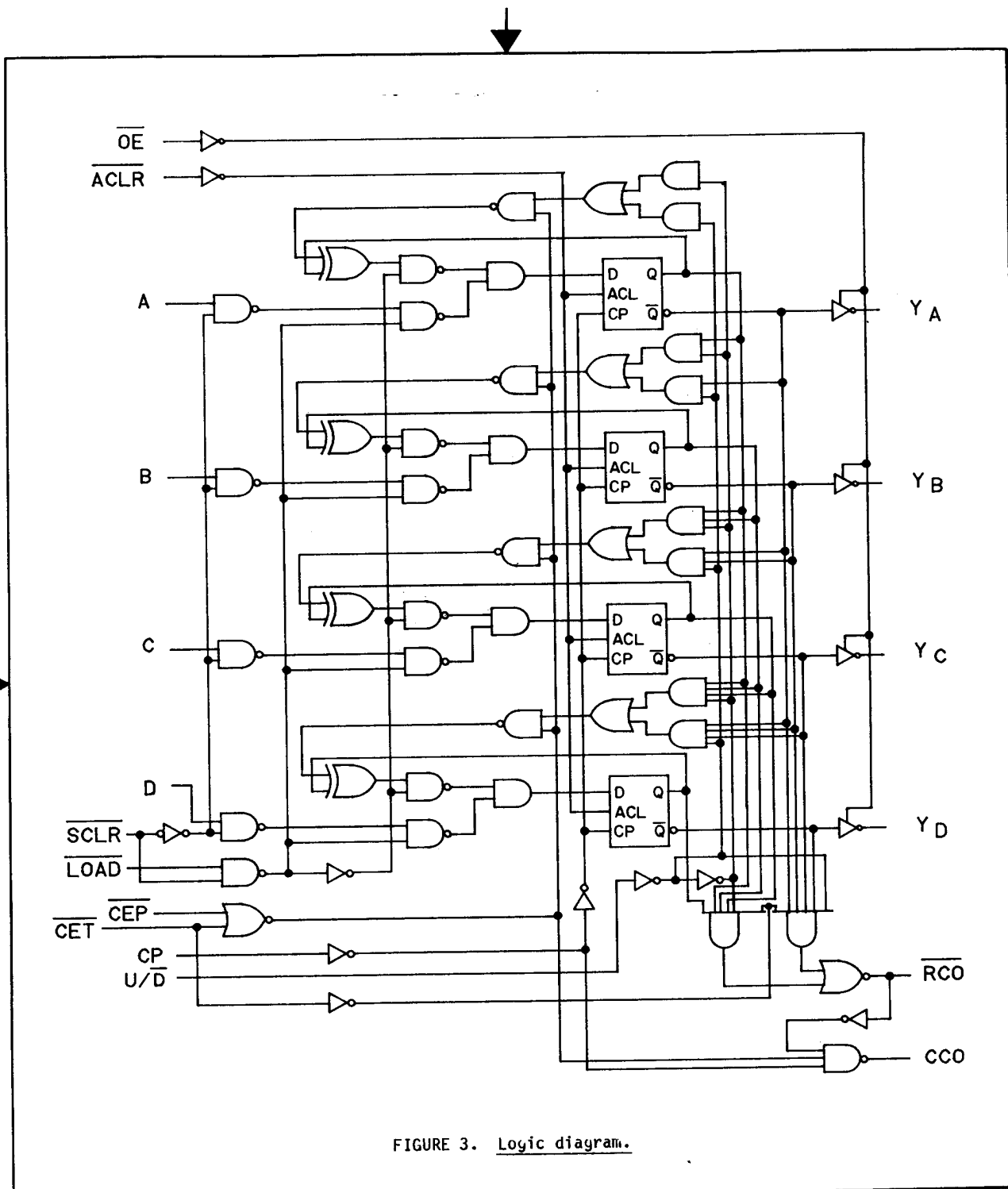
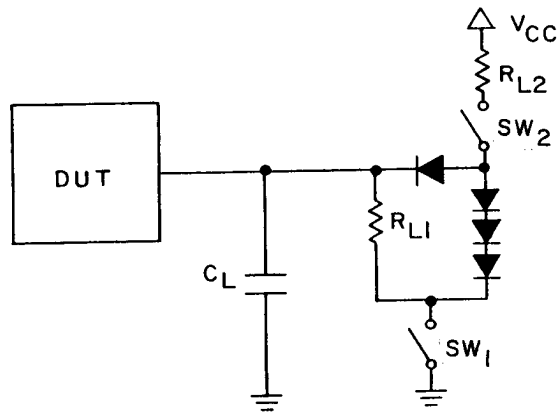


FIGURE 3. Logic diagram.

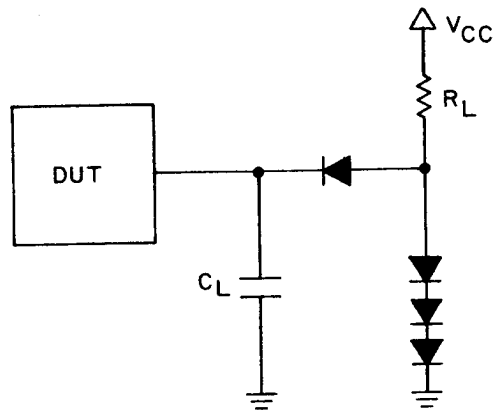
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV A	PAGE 11

DESC FORM 193A
FEB 86

AC Bench load test circuit
for three-state outputs



AC Bench load test circuit
for non three-state outputs



Switch Matrix

Parameter	SW ₁	SW ₂
t _{PLH}	Closed	Closed
t _{PHL}	Closed	Closed
t _{ZL}	Open	Closed
t _{ZH}	Closed	Open
t _{LZ}	Closed	Closed
t _{HZ}	Closed	Closed

FIGURE 4. Switching waveforms and test circuits.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 12

DESC FORM 193A
FEB 86

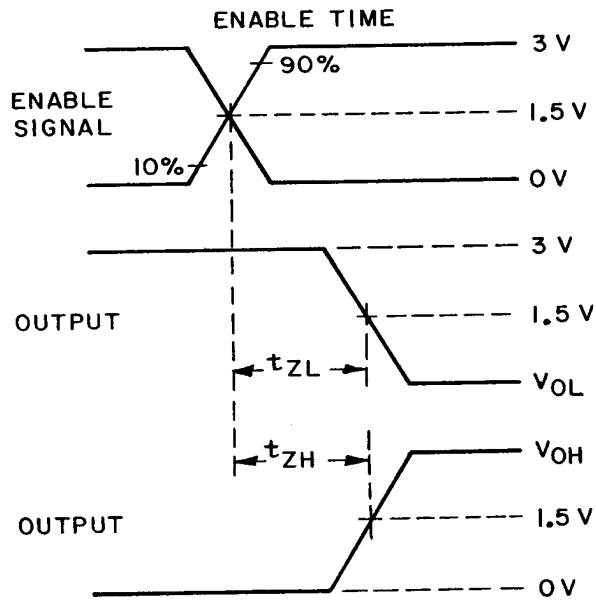
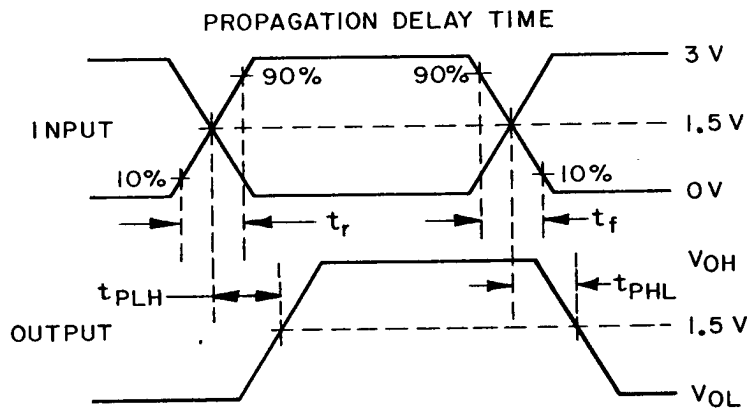
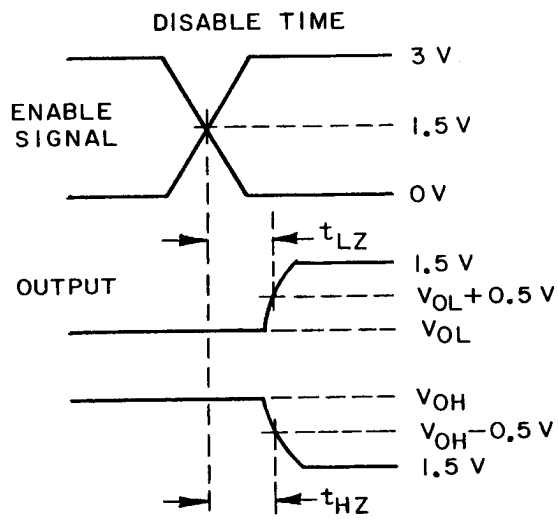


FIGURE 4. Switching waveforms and test circuits - Continued.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 13

DESC FORM 193A
 FEB 86



- NOTES:
1. Pulse generator for all pulses:
 2. Rate < 1.0 MHz; $Z_0 = 50\Omega$; $t_r \leq 15$ ns; $t_f < 6.0$ ns.
 3. C_i Includes probe and jig capacitance.
 4. All diodes are 1N916 or 1N3064.

FIGURE 4. Switching waveforms and test circuits - Continued.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV A	PAGE 14

DESC FORM 193A
 FEB 86

3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. **QUALITY ASSURANCE PROVISIONS**

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test (method 1015 of MIL-STD-883).

(1) Test condition C or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) $T_A = +125^\circ\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroups 7 and 8 tests shall verify the truth table.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test (method 1005 of MIL-STD-883) conditions:

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) $T_A = +125^\circ\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV A	PAGE 15

DESC FORM 193A
FEB 86

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

- * PDA applies to subgroup 1.
- ** Subgroups 10 and 11, if not tested shall be guaranteed to the limits specified in table I.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A		DWG NO. 5962-87544
		REV A	PAGE 16

DESC FORM 193A
FEB 86

6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1/</u>
5962-8754401RX	34335	AM25LS2569/BRA
5962-8754401SX	34335	AM25LS2569/BSA
5962-87544012X	34335	AM25LS2569/B2C

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34335

Vendor name and address

Advanced Micro Devices, Inc.
901 Thompson Place
P.O. Box 3453
Sunnyvale, CA 94088

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	DWG NO. 5962-87544
	REV	PAGE 17

DESC FORM 193A
FEB 86